CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS

REUSABLE THERMAL SOLUTION ATTACHMENT MECHANISM AND METHODS OF USING SAME
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"Brief Description of the Drawings" beginning on page 2, line 21 through page 3, line 15:

Brief Description of the Drawings

Figure 1 is an exploded perspective view of a thermal solution attachment mechanism in one embodiment of the present invention.

Figure 2 is a plan view of a backing plate in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 3A is a plan view of a locking post in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 3B is a plan view of an alternative locking post in one embodiment of the present invention.

Figure 3C is a plan view of another alternative locking post in one embodiment of the present invention.

Figure 4 is a plan view of a mounting plate having slots in the thermal solution attachment mechanism of Figure 1 in one embodiment of the present invention.

Figure 5A is a cut-away perspective view of the slots in the mounting plate of Figure 4 in one embodiment of the present invention.

Figure 5B is a cut-away perspective view of alternative slots in an alternative mounting plate in one embodiment of the present invention.

Figures 6A-6E are schematic illustrations showing a sequence of assembly steps for assembling the thermal solution attachment mechanism of Figure 1 and securing a thermal solution thereon in one embodiment of the present invention.

Figure 7 is a block diagram of various methods for securing a thermal solution attach mechanism to a circuit board in one embodiment of the present invention.

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Figure 8 is a block diagram of a method for temporarily attaching a thermal solution to a processor in one embodiment of the present invention.

Figure 9 is an exploded perspective view of an alternative thermal solution attachment mechanism in one embodiment of the present invention.

The paragraph beginning on page 9, line 11:

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In an alternative embodiment, shown in Figure 9, there is no backing plate and the attachment mechanism is used with a circuit board 102 at least about two (2) cm thick, such as the type of circuit board used in the desktop manufacturing test environment or in a hard mount permanent desktop setting. The securing holes 914 for the locking pins 105 in this embodiment are provided in the circuit board 102 itself. In yet another embodiment, there are no through-holes on the circuit board, and any type of connecting means, such as hooks, screws, nuts and bolts, nails, and so forth, are used to secure the attachment mechanism to the processor.